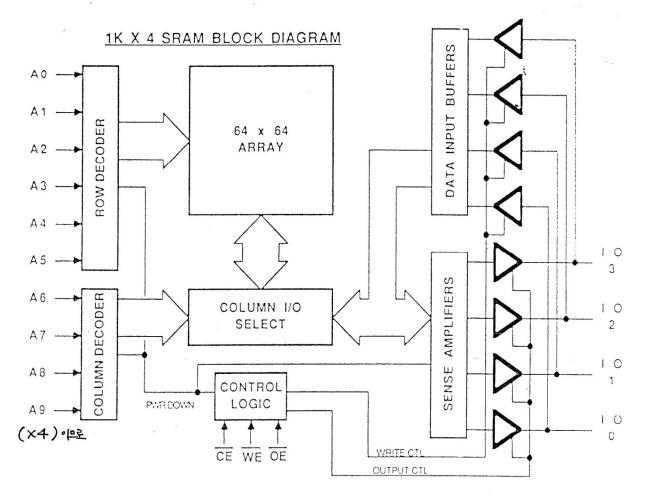
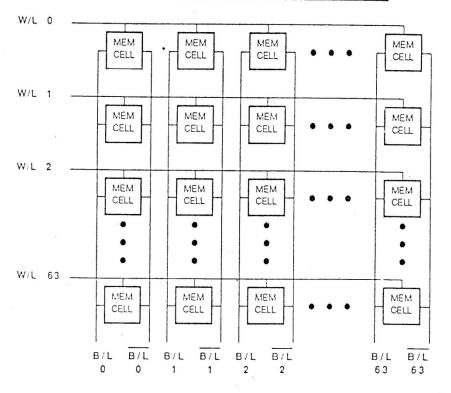
Static Random Access Memories (sRAM) Instructor - Bruce Bateman, Cypress Semiconductor

- Basic Architecture
- Storage Cell
- Address Decoding
- Data Sensing
- READ/WRITE Control

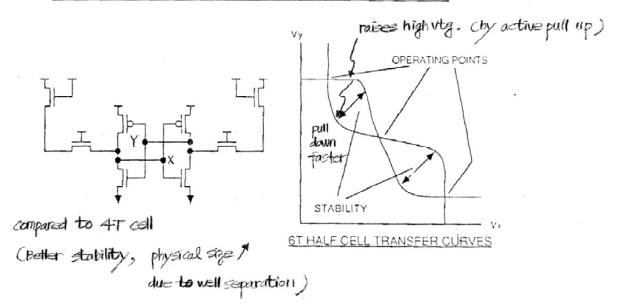


SRAM.

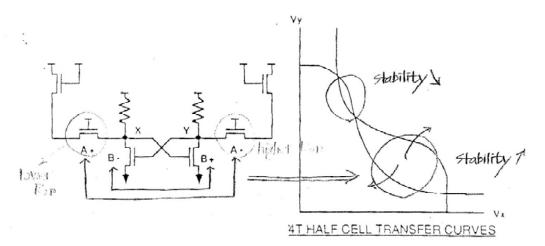
4K SRAM MEMORY ARRAY



6T MEMORY CELL "READ" STABILITY



MEMORY CELL ASYMETRY



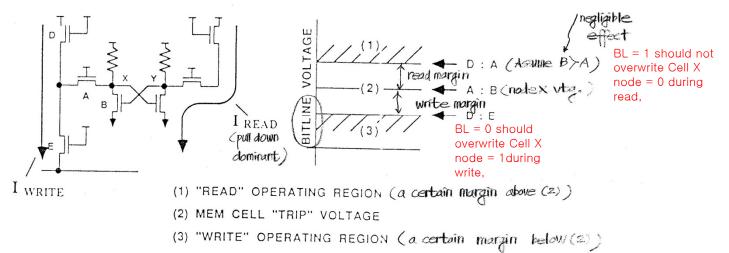
CAUSES:

- . DESIGN MISMATCH DIFFERENT LAYOUT/SIZE
- PROCESS MISMATCH VI, CDs. ETC
 ALIGNMENT SENSITIVITY WIDTH, LENGTH

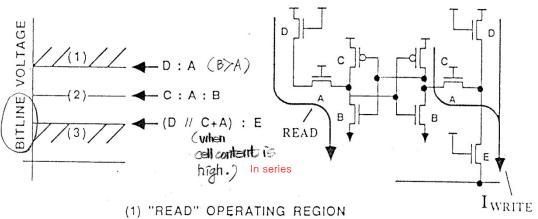
Forting dimension

4T MEMORY CELL READ/WRITE OPERATION

Imagine voltage divider

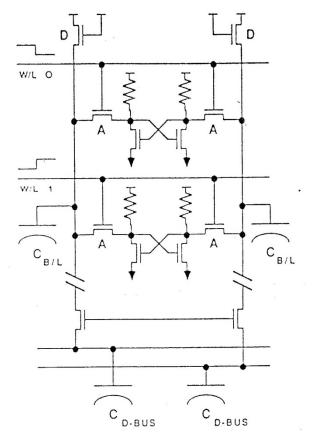


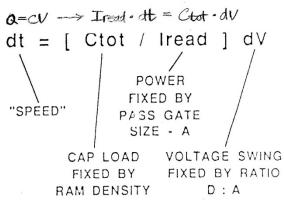
MEMORY CELL READ/WRITE OPERATION



- (1) "READ" OPERATING REGION
- (2) MEM CELL "TRIP" VOLTAGE
- (3) "WRITE" OPERATING REGION

MEMORY CELL SPEED VR. POWER





During read, B effect is negligible since it is large

DRAM - Dynamic Random-Access Memory

1988 IEDM Short Course on Microprocessor and Memories

Nicky C.-C. Lu

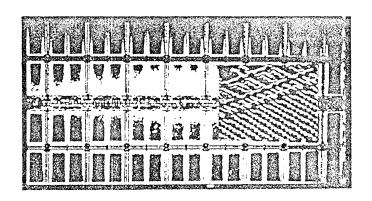
Research Division
Thomas J. Watson Research Center, Yorktown Heights, NY 10598

1. DRAM And Its Development

- 1.1 Background And Definition
- 1.2 DRAMs in Systems: Examples
- 1.3 Product Environments And Trends

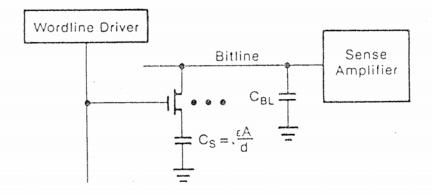
DRAM Chip

- Cell Arrays And Peripheral Circuits
- Array Utilization = (Cell Area × Total Bits)/(Chip Area)
- Key: Small Cell Area,



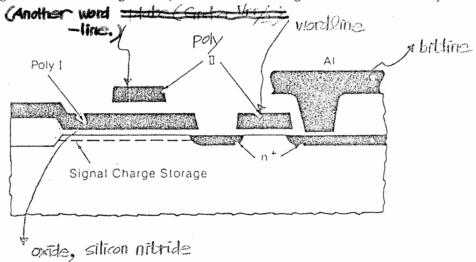
One-Transistor Cell

- An Access Transistor Plus A Storage Capacitor
 - Selected By Wordline
 - Signal Developed on Bitline



Planar Cell Structure

- Planar Transistor Plus Planar Capacitor in Silicon
- Uses Two Polysilicon Layers
- Storage-Node Leakage Requires Refreshing Data Periodically

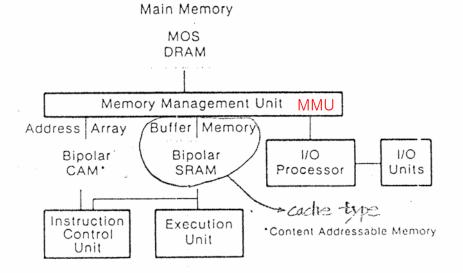


DRAM Definition

- Randomly Addressable Memory (Versus Serial Memory)
- Electrically Read and Write Data at Will in Any Sequence
- Needs Refresh Periodically
- Volatile (Unless By Battery Backup)

DRAM in Mainframe

- Today: ≃1GB (8,000 1Mb DRAM Chips)
- By 1995: ≥64GB (Needs 8,000 64Mb DRAM Chips)



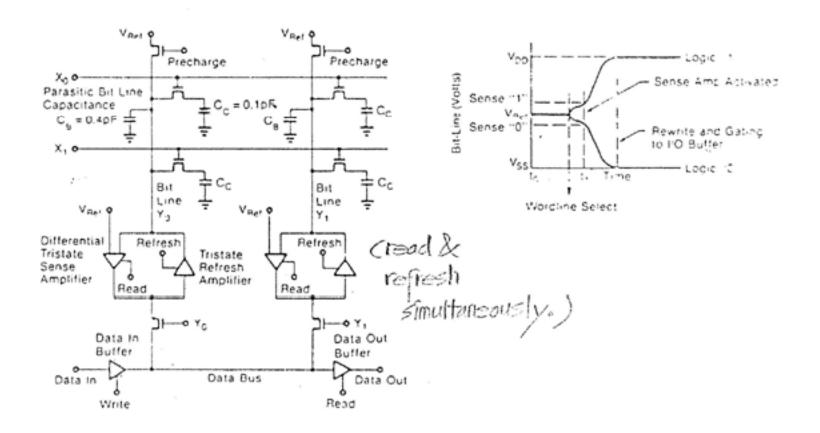
(Figure from Ref. B-6)

Nicky Lu 8/88

2. Chip/Circuit Design

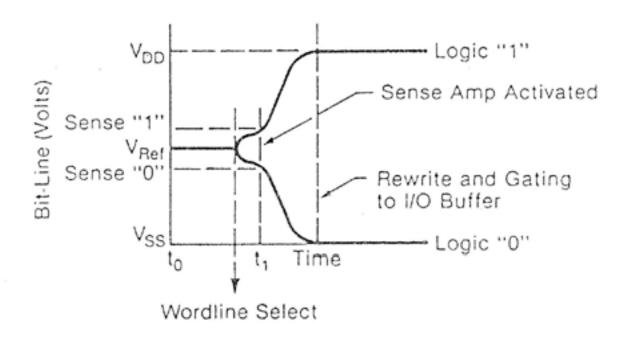
- 2.1 Basic DRAM Operations
- 2.2 Design Example: A 512Kb CMOS High Speed DRAM
- 2.3 Notes on NMOS and BiCMOS DRAMs

Basic Array Design



(After Ref.)

Signal Development



Charge Transfer Ratio Concept (During Read)

• Storage Charge Capacity $Q_s = C_sV_s = 2(C_s + C_B)V_{sen}$

Cell Design Basics

•
$$V_{sen} + \Delta V = \frac{1}{2(C_S + C_B)} \cdot \frac{\epsilon_A V_S}{d}$$

Where AV: Noise

ε: Dielectric Constants

A: Storage Area

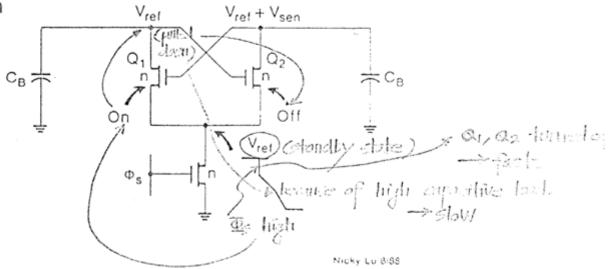
V_S: Storage Signal

d: Dielectric Thickness

V_s/d Limited By Maximum Dielectric Strength

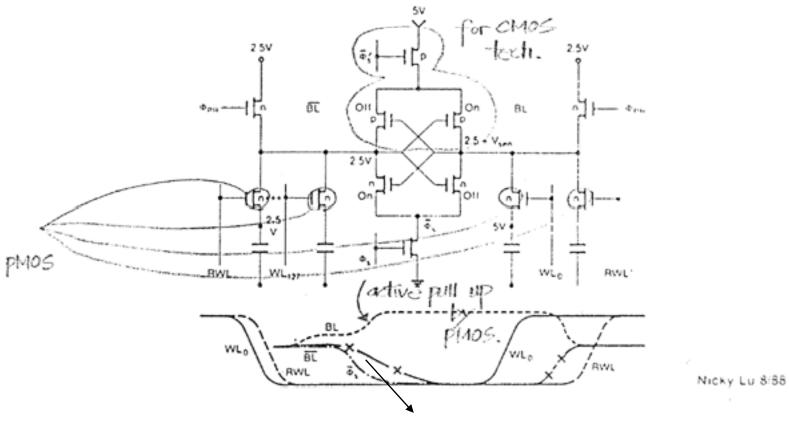
Cross-Coupled Sense Amplifier

- · Differential Signal Established
- Latching
- Amplification



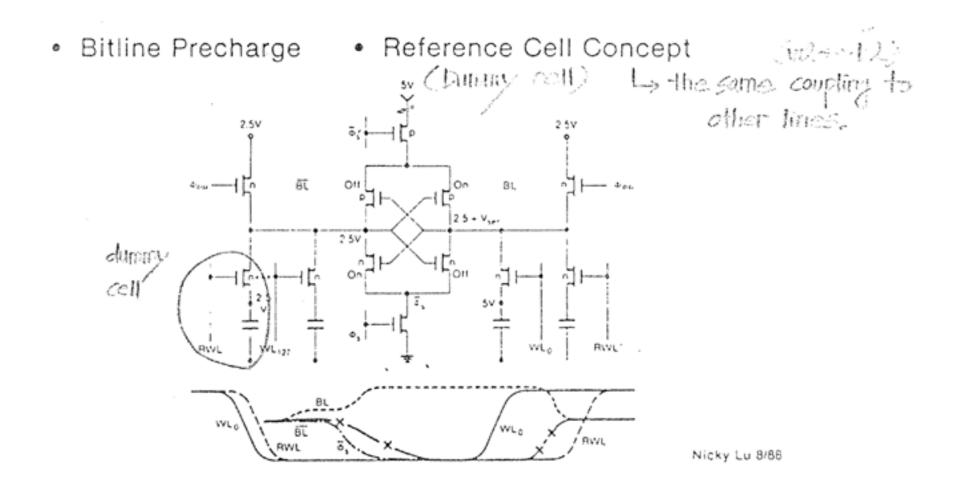
Sensing Circuits

CMOS Cross-Coupled Latch



Phi pulled down then bit line change

Sensing Circuits



Sensing Circuits

• Self Restore • Refresh

Solf Restore • Refresh

The state of the sta

Nicks Lu 5 55